

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	72822	(semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) same ((underfill or (under adj fill) or (under-fill) or resin or epoxy) with (mold or molding or molded or case))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 09:31
L3	53671	(semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) with ((underfill or (under adj fill) or (under-fill) or resin or epoxy) with (mold or molding or molded or case))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 09:31
L4	28575	(semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) near5 ((underfill or (under adj fill) or (under-fill) or resin or epoxy) near5 (mold or molding or molded or case))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 09:31
L5	11587	(semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) near2 ((underfill or (under adj fill) or (under-fill) or resin or epoxy) near2 (mold or molding or molded or case))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 09:32
L6	662	(semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) adj ((underfill or (under adj fill) or (under-fill) or resin or epoxy) adj (mold or molding or molded or case))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 10:30
L7	327	29/856.CCIs.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 10:30
L8	1713	438/127.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 10:42

EAST Search History

S1	102072	(semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) and ((underfill or (under adj fill) or (under-fill) or resin or epoxy) with (mold or molding or molded or chase))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/21 09:29
S2	10481	"257"/\$6.ccls. and ((semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) and ((underfill or (under adj fill) or (under-fill) or resin or epoxy) with (mold or molding or molded or chase)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 14:51
S3	4116	"438"/\$6.ccls. and ((semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) and ((underfill or (under adj fill) or (under-fill) or resin or epoxy) with (mold or molding or molded or chase)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 14:51
S4	8681	"257"/\$6.ccls. and ((semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) and ((underfill or (under adj fill) or (under-fill) or resin or epoxy) near3 (mold or molding or molded or chase)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 14:56
S5	3300	"438"/\$6.ccls. and ((semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) and ((underfill or (under adj fill) or (under-fill) or resin or epoxy) near3 (mold or molding or molded or chase)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 14:55
S6	3300	"438"/\$6.ccls. and ((semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) and ((underfill or (under adj fill) or (under-fill) or resin or epoxy) near3 (mold or molding or molded)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 14:53
S7	1781	"438"/\$6.ccls. and ((semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) and ((underfill or (under adj fill) or (under-fill) or resin or epoxy) near3 (mold or molding or molded)))	USPAT	OR	ON	2007/06/20 16:56

EAST Search History

S8	133	"438"/\$6.ccls. and ((semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) and ((underfill or (under adj fill) or (under-fill)) near3 (mold or molding or molded or chase)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04
S9	194	"257"/\$6.ccls. and ((semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) and ((underfill or (under adj fill) or (under-fill)) near3 (mold or molding or molded or chase)))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 16:57
S10	272	S8 S9	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 15:03
S12	332	257/795.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 15:03
S13	3982	257/787.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 15:05
S14	932	257/687.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 15:05
S15	584	257/667.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 15:07

EAST Search History

S16	35	257/e23.116.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 15:08
S17	39	257/e23.123.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 15:08
S18	282	257/e23.129.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 15:26
S19	5731	S12 S13 S14 S15 S16 S17 S18	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 15:17
S20	2629	257/e21.503.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 15:26
S21	2061	257/e21.504.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 15:27
S22	1677	438/127.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 15:28

EAST Search History

S23	5845	S20 S21 S22	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 15:28
S24	10701	S23 S19	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/28 15:28
S25	1800	S24 and (underfill or (under adj fill) or (under-fill))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04
S26	1	"6724084".PN.	USPAT; USOCR	OR	OFF	2007/03/28 16:27
S27	1	"6462420".PN.	USPAT; USOCR	OR	OFF	2007/03/28 16:27
S28	1	"5734199".PN.	USPAT; USOCR	OR	OFF	2007/03/28 16:27
S29	1	"5523628".PN.	USPAT; USOCR	OR	OFF	2007/03/28 16:27
S30	122	("438"/\$6.ccls. and ((semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) and ((underfill or (under adj fill) or (under-fill) or resin or epoxy) near3 (mold or molding or molded)))) and @pd>"20070328"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:12
S31	9	("257"/\$6.ccls. and ((semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) and ((underfill or (under adj fill) or (under-fill)) near3 (mold or molding or molded or chase)))) and @pd>"20070328"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 16:57
S32	6	("438"/\$6.ccls. and ((semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) and ((underfill or (under adj fill) or (under-fill)) near3 (mold or molding or molded or chase)))) and @pd>"20070328"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04

EAST Search History

S33	335	257/795.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04
S34	4028	257/787.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04
S35	945	257/687.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04
S36	591	257/667.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04
S37	46	257/e23.116.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04
S38	41	257/e23.123.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04
S39	287	257/e23.129.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04

EAST Search History

S40	5808	S33 S34 S35 S36 S37 S38 S39	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04
S41	2745	257/e21.503.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04
S42	2101	257/e21.504.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04
S43	1711	438/127.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04
S44	6015	S41 S42 S43	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04
S45	10936	S44 S40	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04
S46	22	(S45 and (underfill or (under adj fill) or (under-fill))) and @pd>"20070328"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:04

EAST Search History

S47	6	("438"/\$6.ccls. and ((semiconductor or ic or chip or die or (electronic adj device) or (integrated adj circuit)) and ((underfill or (under adj fill) or (under-fill)) near3 (mold or molding or molded or chase)))) and @pd>"20070328"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:05
S48	148	S30 S31 S32 S46 S47	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/06/20 17:13